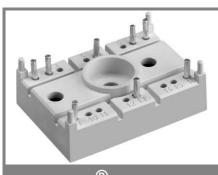
# SK 9 GD 065



SEMITOP<sup>®</sup> 2

### **IGBT** Module

#### SK 9 GD 065

Preliminary Data

### Features

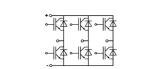
- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- Ultrafast NPT technology IGBT
- CAL technology FWD

#### **Typical Applications**

- Switching ( not for linear use )
- Inverter
- Switched mode power supplies
- UPS

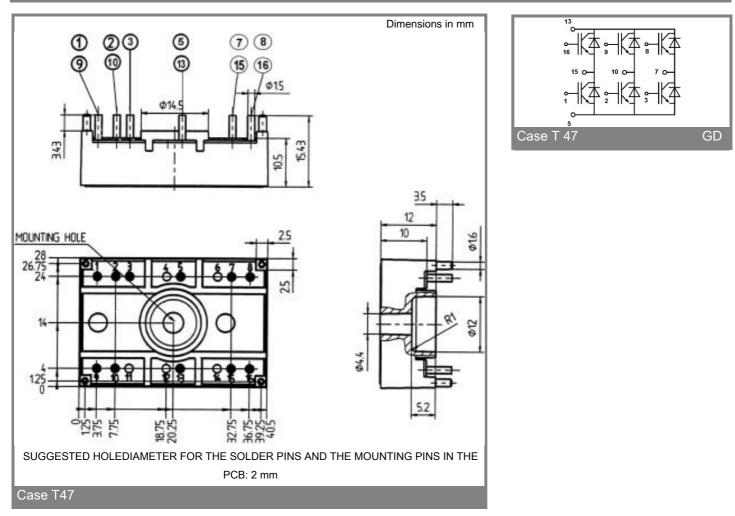
Absolute Maximum Ratings		T <sub>s</sub> = 25 °C, unless otherwise specified					
Symbol	Conditions	Values U					
IGBT							
V <sub>CES</sub>		600	V				
V <sub>GES</sub>		± 20	V				
I <sub>C</sub>	T <sub>s</sub> = 25 (80) °C;	11 (8)	А				
I <sub>CM</sub>	t <sub>p</sub> < 1 ms; T <sub>s</sub> = 25 (80) °C;	22 (16)	А				
Т <sub>ј</sub>		- 40 + 150	°C				
Inverse/Freewheeling CAL Diode							
I <sub>F</sub>	T <sub>s</sub> = 25 (80) °C;	22 (15)	А				
$I_{FM} = -I_{CM}$	t <sub>p</sub> < 1 ms; T <sub>s</sub> = 25 (80) °C;	44 (30)	А				
T <sub>j</sub>		- 40 + 150	°C				
T <sub>stg</sub>		- 40 + 125	°C				
T <sub>sol</sub>	Terminals, 10 s	260	°C				
V <sub>isol</sub>	AC 50 Hz, r.m.s. 1 min. / 1 s	2500 / 3000	V				

Characteristics		T <sub>s</sub> = 25 °C	$T_s$ = 25 °C, unless otherwise specified				
Symbol	Conditions	min.	typ.	max.	Units		
IGBT							
V <sub>CE(sat)</sub>	I <sub>C</sub> = 6 A, T <sub>i</sub> = 25 (125) °C		2 (2,2)	2,5 (2,7)	V		
V <sub>GE(th)</sub>	$V_{CE} = V_{GE}$ ; $I_{C} = 0,0005 \text{ A}$	3	4	5	V		
C <sub>ies</sub>	$V_{CE}^{0}$ = 25 V; $V_{GE}$ = 0 V; 1 MHz		0,32		nF		
R <sub>th(j-s)</sub>	per IGBT			2,6	K/W		
	per module				K/W		
	under following conditions:						
t <sub>d(on)</sub>	$V_{CC}$ = 300 V , $V_{GE}$ = ± 15 V		20		ns		
t <sub>r</sub>	I <sub>C</sub> = 6 A, T <sub>j</sub> = 125 °C		25		ns		
t <sub>d(off)</sub>	$R_{Gon} = R_{Goff} = 120 \Omega$		145		ns		
t <sub>f</sub>			25		ns		
$E_{on} + E_{off}$	Inductive load		0,34		mJ		
Inverse/Freewheeling CAL Diode							
	I <sub>F</sub> = 15 A; T <sub>i</sub> = 25 (125) °C		1,4 (1,4)	1,7 (1,7)	V		
V <sub>(TO)</sub>	T <sub>j</sub> = 25 (125) °C		1 (0,9)	1,1 (1)	V		
r <sub>T</sub>	T <sub>j</sub> = 25 (125) °C		30 (33)	40 (47)	mΩ		
R <sub>th(j-s)</sub>				2,3	K/W		
	under following conditions:						
I <sub>RRM</sub>	I <sub>F</sub> = 15 A; V <sub>R</sub> = 300 V		22		А		
Q <sub>rr</sub>	dI <sub>F</sub> /dt = 1100 A/µs		1,5		μC		
E <sub>off</sub>	V <sub>GE</sub> = 0 V; T <sub>j</sub> = 125 °C		0,31		mJ		
Mechanical data							
M1	mounting torque			2	Nm		
w			21		g		
Case	SEMITOP <sup>®</sup> 2		T 47				



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## SK 9 GD 065



This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

This technical information specifies semiconductor devices but promises no characteristics. No warranty or guarantee expressed or implied is made regarding delivery, performance or suitability.